This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-5   (Canceled)

Claim 6.   (Original)   A method for preventing electrostatic damages to a semiconductor chip package during storage, the package having a plurality of terminals, the method comprising:

forming one or more conductive members electrically connecting the terminals to each other; and

disabling the electrical connections by an action of mounting the package on a printed circuit board.

Claim 7.   (Original)   The method of claim 6, wherein the step of forming the conductive members comprises forming solder members connecting the terminals, and wherein the action of mounting the package comprises soldering the terminals.

Claim 8.   (Original)   The method of claim 7, wherein the step of forming the conductive members comprises forming solder lines connecting the terminals.

Claim 9.   (Original)   The method of claim 7, wherein the step of forming the conductive members comprises forming a conductive thin film.

Claim 10.   (Original)   The method of claim 6, wherein the terminals are pin-shaped having protruding tips, and the step of forming the conductive members comprises forming conductive wires connected at the tips of the terminals, and wherein the action of mounting the package comprises inserting the terminals into sockets.

Claim 11.   (New)   The method of claim 6, wherein the step of disabling the electrical connections comprises melting the connection by heat.

Claim 12.   (New)   The method of claim 9, wherein the step of forming the conductive thin film comprises patterning the conductive thin film by a photolithography process and an etching process.

Claim 13.   (New)   The method of claim 8, the solder lines is formed to a net-like structure.

Claim 14.   (New)   The method of claim 8, the solder lines is formed to a single line-like solder member.

Claim 15.   (New)   The method of claim 9, the step of forming the conductive thin film comprises forming the conductive thin film on the terminals.